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(54) **CIRCUIT BOARD**

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(57) **ABSTRACT**

A circuit board includes a substrate and a first metal circuit layer. The substrate has an upper surface and a lower surface opposite to the upper surface. The first metal circuit layer is located on the upper surface, and the first metal circuit layer includes a first line area and a second line area. The first line area and the second line area are separated by a groove area, and the groove area includes a bent section. Accordingly, the risk of detachment between the first metal circuit layer and the substrate due to stress concentration on the circuit board can be reduced.

